PCN Number:		20170118005				PCN Date:	Feb. 14, 2017			
Title: Datasheet for ISO5851										
Custom	PCN Manager					D	Dept:		Quality Services	
Change Type:										
Assembly Site				Design				Wafer	Bump Site	
Assembly Process			\boxtimes	Data She	et			Wafer	Bump Material	
Assembly Materials				Part num	ber change			Wafer	Bump Process	
Mechanical Specification			Test Site				Wafer	Fab Site		
Packing/Shipping/Labeling				Test Proc	ess			Wafer	Fab Materials	
									Wafer	Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



ISO5851 SLLSEN5B – JUNE 2015–REVISED JANUARY 2017 Changes from Revision A (June 2015) to Revision B Page Changed the Title From: "Active Safety Features" To: Active Protection Features" 1 Changed Feature From: Surge Immunity 12800-VPK (according to IEC 61000-4-5) To: Isolation Surge Withstand Changed the Thermal Derating Curve for Limiting Current per VDE figure and Added the Thermal Derating Curve Added text ", but connecting CLAMP output of the gate driver to the IGBT gate is also not an issue." to Supply and Deleted text "thereby, providing protection against further catastrophic failures." From: the Global-Shutdown and The datasheet number will be changing. Change From: Device Family Change To:

These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/ISO5851								
Reason for Change:								
To accurately reflect device characteristics.								
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):								
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.								
Changes to product identification resulting from this PCN:								
None.								
Product Affected:								
ISO5851DW ISO	605851DWR							

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com